



Vincotech

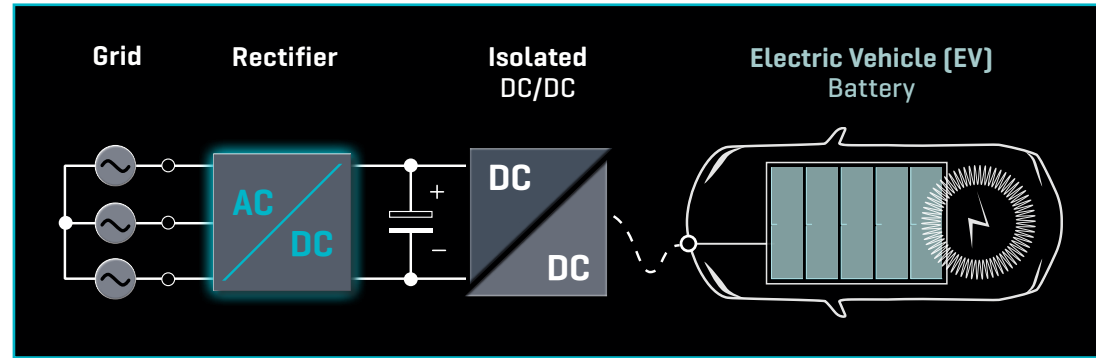
DC FAST CHARGING SOLUTIONS



EMPOWERING YOUR IDEAS

CHARGING THE FUTURE

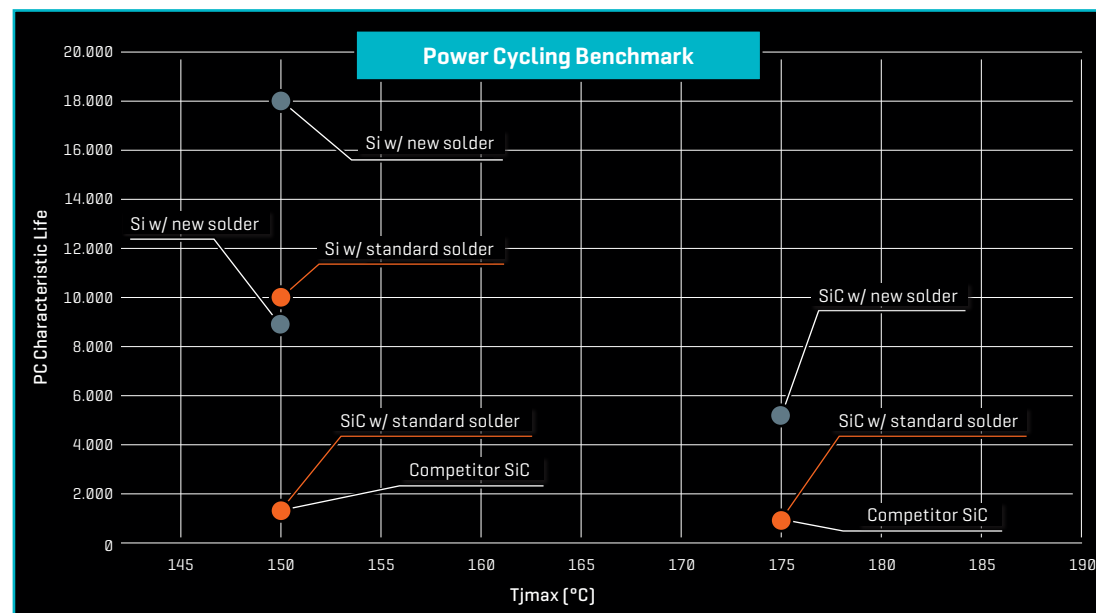
Vincotech is the partner of choice for power modules that support state-of-the-art topologies in a DC fast charger's power stages: the **AC/DC converter** and the **galvanically isolated DC/DC stage**.



State-of-the-art system architecture for DC chargers

Vincotech power modules are well established in many DC Charger applications from EV Charging key players who benefits from:

- / Higher switching frequency, lower filtering effort/costs
- / Multi-sourced SiC-components for more freedom of choice and less supply chain risk
- / Factor >3 improved power cycling capability for higher lifetime
- / Integrated DC capacitors to mitigate voltage overshoot
- / Press-fit pins and pre-applied TIM to help reduce production cost



Key trends/drivers in DC charger engineering:

High power charging stations

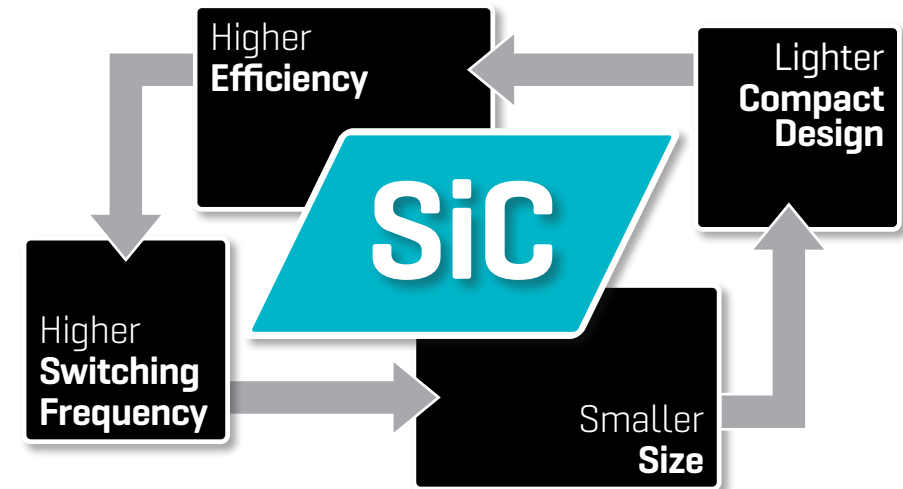
- Charging will shift towards public and workplace options, as more people without access to home charging start to buy EVs. There will be a growing need for DC fast chargers with nominal power beyond 22 kW in the next years.
- Megawatt Charging Systems (MCS) >1MW for electrical heavy-duty vehicles

Battery voltage 400V → 800V

- Wide DC output voltage range [200V → 920V]

Bi-directional charging

- V2L, V2G or V2H



Modular Design

- For >30 kW The modular design is more dominant than the monolithic design approach, giving the benefits of high design flexibility and scalability

Reliability

- More challenging mission profiles

Power module Solution

- for >30 kW The power module solution is more preferred than the discrete solution, thus benefiting from optimal thermal management, simplified mechanical assembly, and low parasitic inductance

Efficiency: from today 95% to 98%

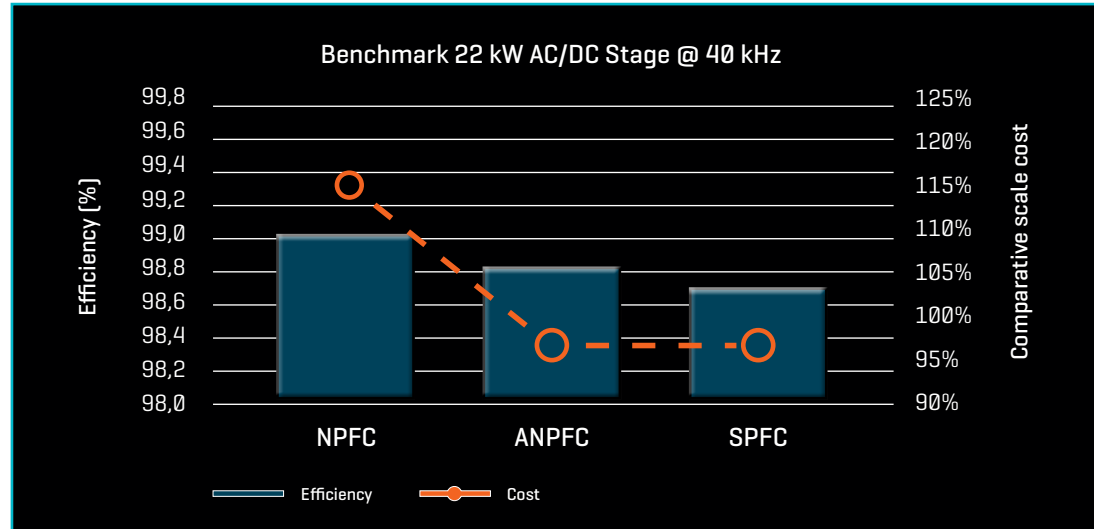
- WBG components are playing a key roll to achieve this goal
- 3% efficiency improvement will save 2,1 billions kWh electricity per year*

* 30million electric vehicles by 2025 / 15000 km annual driven kilometers / average power consumption 15kWh

DC FAST CHARGER

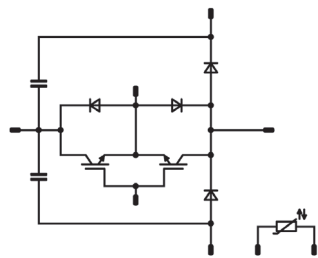
AC/DC Product Portfolio

- / The **front-end three-phase PFC** might be implemented in multiple topologies. It can be distinguished between **two-level** and **three-level** which have an impact on the design and the blocking voltage rating of the semiconductors.
- / Three-level topologies are great for engineers seeking high efficiency at low costs.
- / These topologies are designed for unidirectional charging. Three-level SPFC and NPFC can be adapted for **bidirectional** charging by replacing boost diodes with switches.

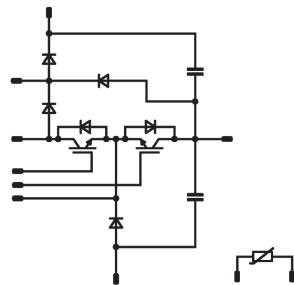


The most common three-level PFC topologies in chargers:

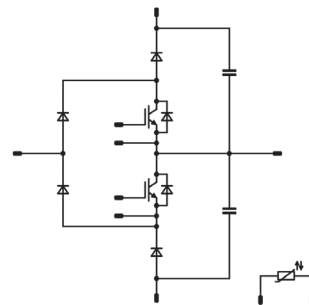
NPFC (Neutral Boost PFC)



ANPFC (Advanced Neutral Boost PFC)



SPFC (Symmetric Boost PFC)



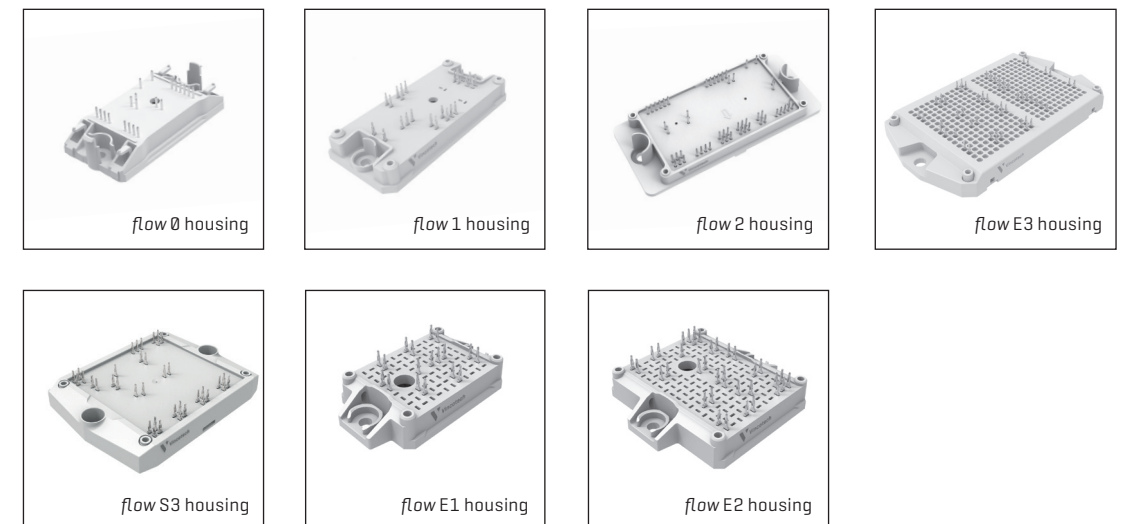
Comprehensive 2L and 3L PFC portfolio for the AC/DC stage

- / SiC MOSFET and fast IGBT chip technology for high-speed switching and greater efficiency
- / Kelvin emitter for better switching performance
- / Integrated DC capacitor to reduce voltage overshoot
- / High-power, low-inductive package
- / Temperature sensor

	ANPFC (T-Type)		NPFC (T-Type)			SPFC (I-Type)
	flowANPFC	flow3xANPFC	flowNPFC	flow3xNPFC	flowMNPC	flowSPFC
3L-PFC	flow 0	25 kW		15 kW [35 kW]*	[30 kW]*	25 kW
	flow 1	35 kW [60 kW]*	15 kW	60 kW [NEW]	20 kW	[60 kW]*
	flow 2		30 kW			
	flow E2				75 kW [NEW]	
	flow S3				[50 kW]*	
	flow E3					[50 kW]*

	Sixpack	Half-Bridge	CSPFC	
	flowPACK SiC	flowDUAL SiC	flowCSPFC	
2L-PFC w/SiC MOSFET	flow 1	22 kW		
	flow E1	10 kW	40 kW	
	flow E2		100 kW	30 kW
	flow E3		150 kW [NEW]	

* in concept

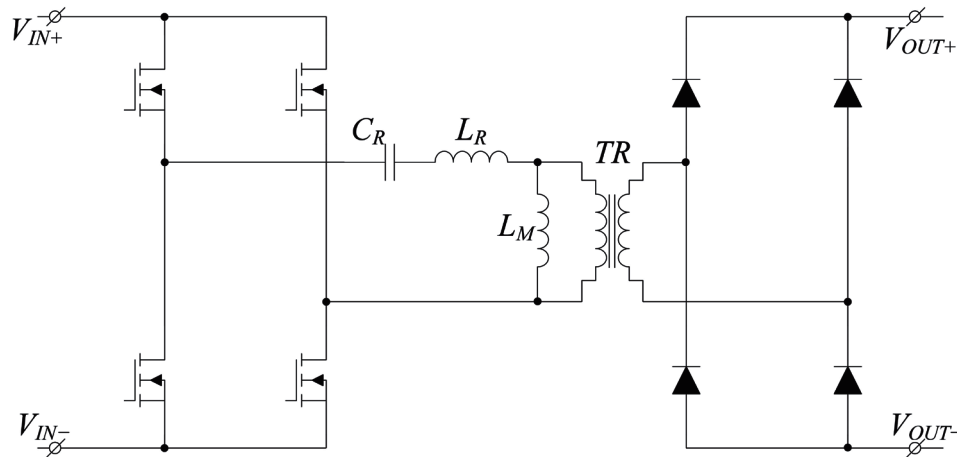


DC FAST CHARGER

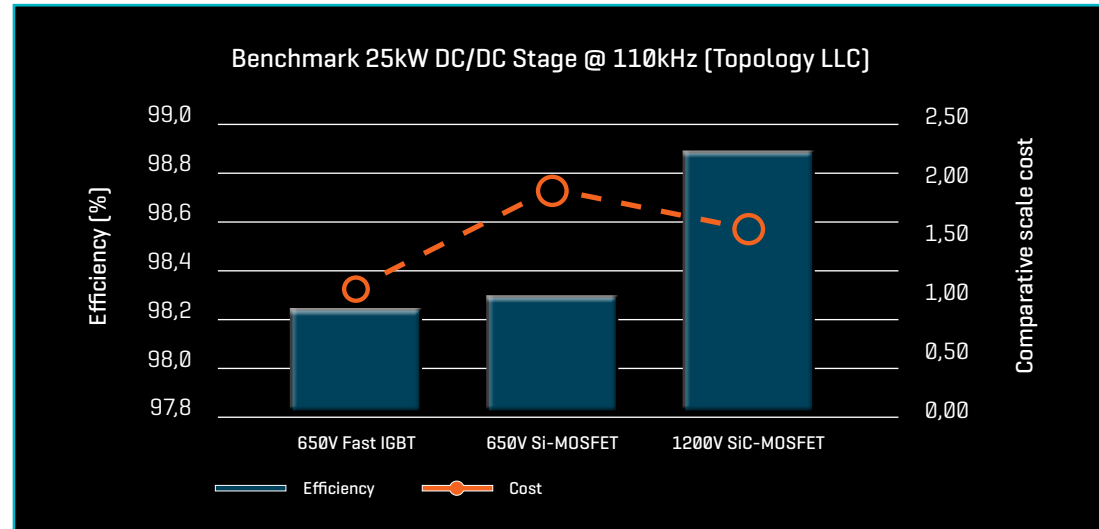
DC/DC Product Portfolio

The most frequently used topology in the isolated DC/DC conversion stage is the **full-bridge resonant LLC converter**. In this stage, **SiC MOSFET chip technology** is essential to meeting switching frequency [>100 kHz] and peak efficiency [$>98.5\%$] requirements.

A 1200-V SiC MOSFET streamlines the topology by transitioning from a two cascaded interleaved LLC with 650V Si components to a single full-bridge LLC.



Full-bridge LLC converter with a full-bridge rectifier



If the application requires very high efficiency, the full-bridge [2-level] with 1200 V SiC-MOSFET would be the configuration of choice. The price decrease of this chip technology over the last years favours this option also from cost point of view

Vincotech *fastPACK* products

- / Integrated DC capacitor to reduce voltage overshoot
- / Kelvin emitter for better switching performance
- / SiC MOSFET and fast IGBT chip technology for high-speed switching and greater efficiency
- / Open or common emitter configuration
- / High-power, low-inductive package

Wide H-bridge SiC MOSFET portfolio for the DC/DC primary stage

		<i>fastPACK</i> SiC		
		650 V	950 V	1200 V
H-Bridge w/SiC MOSFET	flow 0		15 kW	10 kW
	flow 1			[50 kW] *
	flow E1			25 kW [NEW]
	flow E2			50 kW

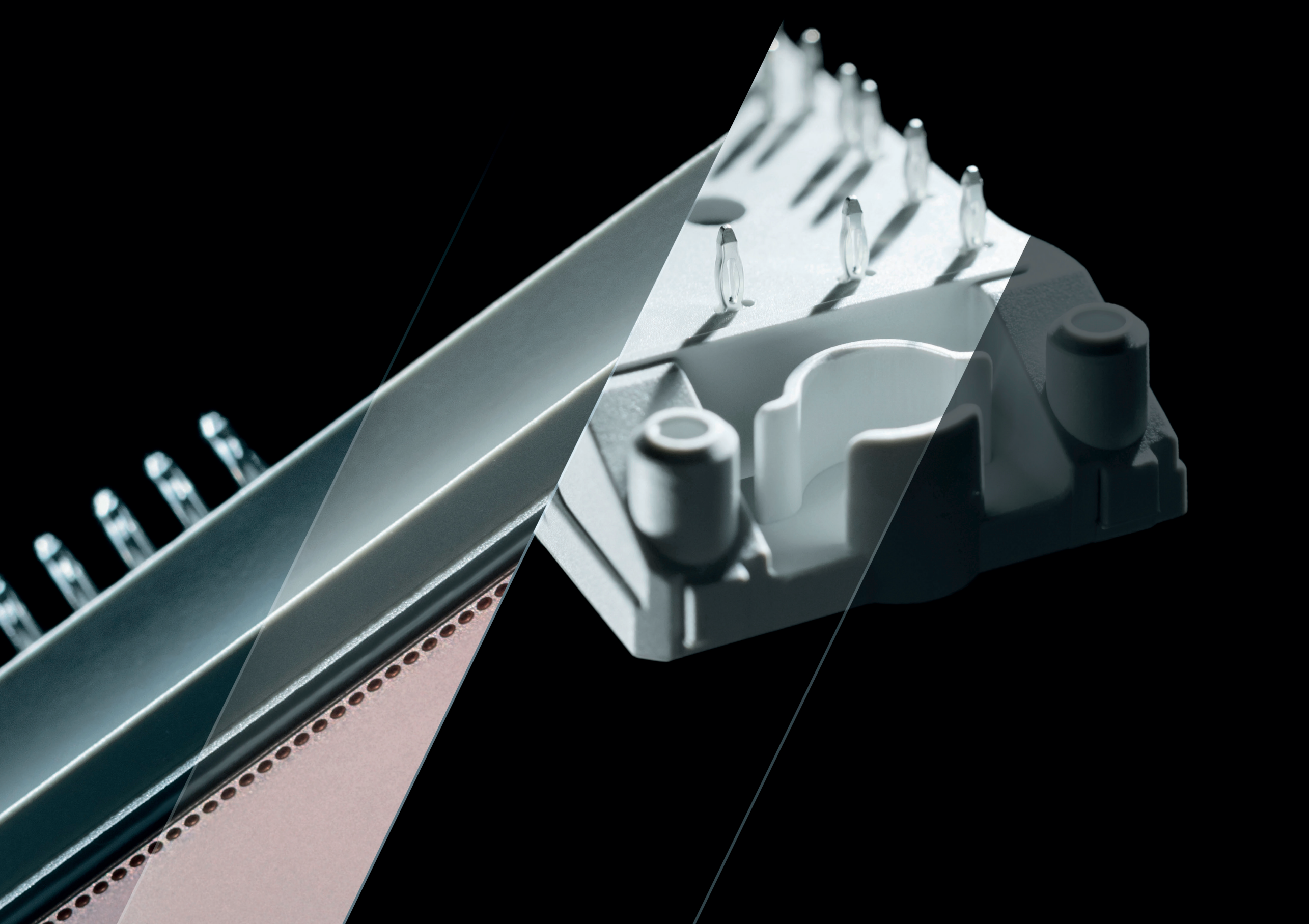
		<i>fastPACK</i>		
		650 V	950 V	1200 V
H-Bridge w/IGBT fast	flow 0	22 kW [NEW]		22 kW [NEW]
	flow 1	30 kW		22 kW [NEW]

Ultrafast rectifier-bridge portfolio for the DC/DC secondary stage

		<i>fastPACK</i> SiC		
		650 V	1200 V	1700 V
Rectifier-Bridge w/SiC Diode	flow 0	15 kW		
	flow 1	30 kW	50 kW [NEW]	
	flow E1		25 kW	15 kW
	flow E2		[50 kW] *	
	flow S3		50 kW [NEW]	

		<i>fastPACK</i>		
		650 V		1200 V
Rectifier-Bridge w/ fast Diode				30 kW
		50 kW		

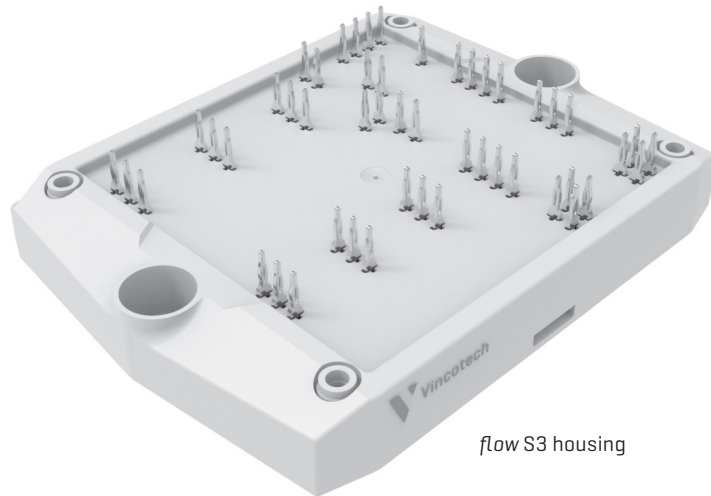
* in concept



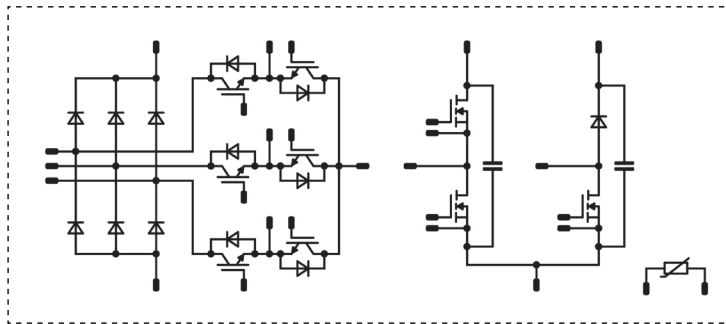
New *flow*CSPFC S3 SiC

- / **New Current Synthesizing PFC (CSPFC) topology** for highest efficiency at lowest total system costs through
 - Reduced number of SiC devices
 - Reduced number and size of the PFC inductors
- / **Latest SiC-MOSFET chip technology** for high speed switching and high efficiency up to 100 kHz and >99% respectively
- / Bi-directional ready
- / Thin Al₂O₃ substrate eases the system's thermal design
- / Temperature sensor

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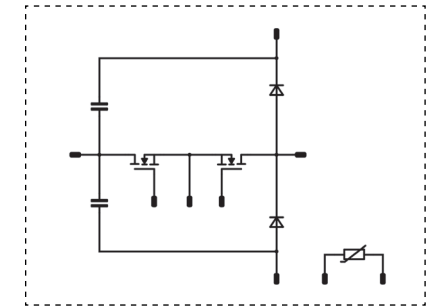
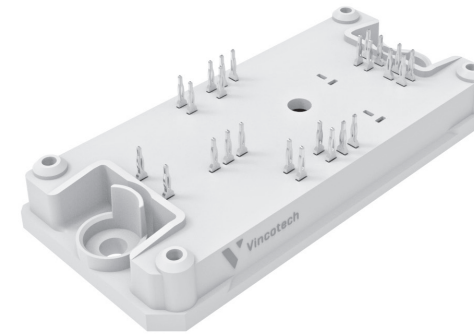
flow S3 housing



New *flow*NPFC 1 SiC

- / **Optimised layout/pinout** for SiC MOSFET use
 - Lower stray inductance
 - Optimal commutation loops
- / **SiC MOSFET Gen3 chip technology** for high speed switching and highest efficiency

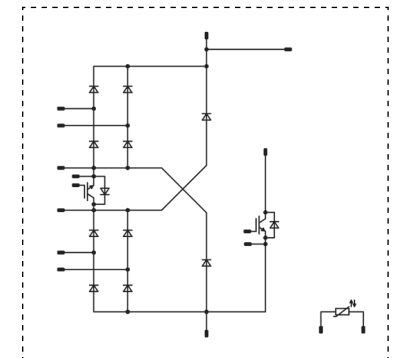
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*fast*PACK S3 SiC

- / Ready for 400 V and 800 V battery systems
- / Latest generation SiC SBD for high switching and high efficiency
- / Optional w/ or w/o discharge switch

B0-SP120RA080R0-LM90J48T





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